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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/616,227	07/10/2003	Kazuhiko Nagano	Q76484	2250
23373	7590	03/13/2008	EXAMINER	
SUGHRUE MION, PLLC			VAN ROY, TOD THOMAS	
2100 PENNSYLVANIA AVENUE, N.W.				
SUITE 800			ART UNIT	PAPER NUMBER
WASHINGTON, DC 20037			2828	
			MAIL DATE	DELIVERY MODE
			03/13/2008	PAPER

Please find below and/or attached an Office communication concerning this application or proceeding.

The time period for reply, if any, is set in the attached communication.

Office Action Summary	Application No.	Applicant(s)	
	10/616,227	NAGANO ET AL.	
	Examiner	Art Unit	
	TOD T. VAN ROY	2828	

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

1) Responsive to communication(s) filed on 26 December 2007.

2a) This action is **FINAL**. 2b) This action is non-final.

3) Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

4) Claim(s) 1-3,6-10,12-14 and 27-29 is/are pending in the application.

4a) Of the above claim(s) _____ is/are withdrawn from consideration.

5) Claim(s) _____ is/are allowed.

6) Claim(s) 1-3,6-10,12-14, 27-29 is/are rejected.

7) Claim(s) _____ is/are objected to.

8) Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

9) The specification is objected to by the Examiner.

10) The drawing(s) filed on _____ is/are: a) accepted or b) objected to by the Examiner.

Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).

Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).

11) The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).

a) All b) Some * c) None of:

1. Certified copies of the priority documents have been received.
2. Certified copies of the priority documents have been received in Application No. _____.
3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

* See the attached detailed Office action for a list of the certified copies not received.

Attachment(s)

1) Notice of References Cited (PTO-892)

2) Notice of Draftsperson's Patent Drawing Review (PTO-948)

3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)
Paper No(s)/Mail Date _____.

4) Interview Summary (PTO-413)
Paper No(s)/Mail Date. _____.

5) Notice of Informal Patent Application (PTO-152)

6) Other: _____.

DETAILED ACTION

Response to Amendment

The Examiner acknowledges the amending of claims 1 and 12.

Response to Arguments

Applicant's arguments filed 12/26/2007 have been fully considered but they are not persuasive.

With respect to claim 1, the Applicant has argued that the lens array of Heidel does not contact the defined "lens setting surface" perpendicular to the optical axis of the laser diodes. The Examiner does not agree.

Firstly, the Applicant has noted at pg.11 of the Remarks that the Examiner conceded that the lens setting surface is not perpendicular to the optical axis. The Examiner wishes to clarify that this was regarding the surface definition used in the previous rejection of the claims, and was not meant to serve as an all-encompassing description of the Heidel reference.

The Examiner further is of the belief that the front side of element #25 in fig.1 of Heidel is contacted at the corner via the lens array. The Examiner concedes that this may only be a point-contact situation, but that the claims do not currently limit the type of contact made. Claim language which further defines the type of contact, such as using the term "only along" or "excluding", is recommended to distinguish from that of Heidel.

Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless –

(e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.

Claims 1 and 6 are rejected under 35 U.S.C. 102(e) as being anticipated by Heidel et al. (US 5212707).

With respect to claim 1, Heidel discloses a laser apparatus comprising: a block (fig.1 #12), a plurality of laser diodes respectively having light emission points and being fixed to said block so that the light emission points are aligned along a direction (fig.1 #10), a collimator lens array integrally formed to contain a plurality of collimator lenses which are arranged along a direction and respectively collimate laser beams emitted from said plurality of laser diodes (fig.1 #22,24 each taught to be a collimating lens, col.6 lines 23-39, so together form a lens array, #24 also made of an array of individual pieces), wherein said block has a lens setting surface which is flat (fig.1 #25, outer portion of protrusion), perpendicular to optical axes of said plurality of laser diodes (extending perpendicularly in front of the array), and located on a forward side of said plurality of laser diodes at a predetermined distance from said light emission points, and said collimator lens array is fixed to said block so that an end surface of the collimator lens array is in contact with said lens setting surface (fig.1, an end surface of the lens

array contacts the setting surface at the intersection (corner) of the inner portion and outer portion of #25 as can be seen in fig.1).

With respect to claim 6, Heidel discloses the diode lasers to be single cavity and have a single light emission point (abs., wherein the emission regions are said to be separate for each device, fig.2 and are of a single cavity).

Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

The factual inquiries set forth in *Graham v. John Deere Co.*, 383 U.S. 1, 148 USPQ 459 (1966), that are applied for establishing a background for determining obviousness under 35 U.S.C. 103(a) are summarized as follows:

1. Determining the scope and contents of the prior art.
2. Ascertaining the differences between the prior art and the claims at issue.
3. Resolving the level of ordinary skill in the pertinent art.
4. Considering objective evidence present in the application indicating obviousness or nonobviousness.

Claims 12-13, and 27-29 rejected under 35 U.S.C. 103(a) as being unpatentable over Heidel.

With respect to claims 12 and 27-29, Heidel teaches a laser apparatus comprising: a block (fig.1 #12), a plurality of laser diodes respectively having light

emission points and being fixed to said block so that the light emission points are aligned along a direction (fig.1 #10), a collimator lens array integrally formed to contain a plurality of collimator lenses which are arranged along a direction and respectively collimate laser beams emitted from said plurality of laser diodes (fig.1 #22,24 each taught to be a collimating lens, col.6 lines 23-39, so together form a lens array, #24 also made of an array of individual pieces), wherein said block has a lens setting surface which is flat (fig.1 #25, outer portion of protrusion), perpendicular to optical axes of said plurality of laser diodes (extending perpendicularly in front of the array), and located on a forward side of said plurality of laser diodes at a predetermined distance from said light emission points, and said collimator lens array is fixed to said block so that an end surface of the collimator lens array is in contact with said lens setting surface (fig.1, an end surface of the lens array contacts the setting surface at the intersection (corner) of the inner portion and outer portion of #25 as can be seen in fig.1). Heidel does not teach adjusting a position of each of said plurality of laser diodes in a direction parallel to said optical axes based on information obtained by measurement of a focal length of one of the plurality of collimator lenses corresponding to each of said plurality of laser diodes, and fixing each of the plurality of laser diodes at the adjusted position, or adjusting positions of the lens along the reference surface. It would have been obvious to one of ordinary skill in the art at the time of the invention to adjust the distance of the light source away from the lens based on the focal length as this will maximize the light captured and transmitted by the lens, as is well known and widely practiced in all optical

fields. (Heidel additionally teaches making focal length adjustments when constructing the 2D array embodiment.)

Claim 13 is rejected for the same reasons as given in the rejection to claim 1, as well as claim 12.

Claims 2-3 are rejected under 35 U.S.C. 103(a) as being unpatentable over Heidel in view of Chiappetta et al. (US 6724791).

With respect to claims 2 and 3, Heidel teaches the laser apparatus as outlined in the rejection to claim 1, but does not teach the flatness of the block on which the diodes and lenses are fixed to have a flatness not greater than 0.5 um. Chiappetta teaches a laser apparatus wherein it is taught that heat transfer is maximized when the largest amount of surface area of the object and heat sink are in contact, namely when they are both flat (col.7 lines 9-34). It would have been obvious to one of ordinary skill in the art at the time of the invention to combine the laser apparatus of Heidel with the flat contact area as taught by Chiappetta, to maximize heat transfer to the heat sink for both the lenses and the diodes, and additionally to make the flatness not greater than 0.5 um as it has been found to be within the general skill of a worker in the art to discover the optimum or workable ranges through routine experimentation (i.e. optimizing the degree of flatness, as having been taught by Chiappetta; see MPEP 2144.05 II A - *In re Aller*, 220 F.2d 454, 456, 105 USPQ 233, 235 (CCPA 1955)).

Claims 7-10 are rejected under 35 U.S.C. 103(a) as being unpatentable over Heidel in view of Andrews (US 5640188), and further in view of Andrews et al. (US 5432535) and Kuniyasu et al. (US 2002/0018499).

With respect to claims 7, and 9, Heidel teaches the laser apparatus as outlined in the rejection to claim 1, including the block to be a heat dissipation block. Heidel does not teach the lasers to be mounted on a plurality of submounts which is in turn mounted on the heat dissipation block, or that the semiconductor lasers are mounted on the submounts via AuSn and a metallization layer, and are of a nitride compound. Andrews '188 teaches a plurality of semiconductor lasers mounted on a plurality of submounts (fig.4 #'s 86), said submounts being themselves mounted on a copper heat dissipation block (fig.4 #64, taught to be made of one piece, col.5-6 lines 65-7). Andrews '535 teaches semiconductor laser submounts to be made of AlN (col.5 lines 16-19) and to be at least 200um thick (col.10 line 22). Kuniyasu further teaches the use of GaN based material ([0008]) to be flip chip mounted (fig.28, heat sink attached at top surface), and to be bonded to a heat sink through a metallization layer (fig.32 #258) and AuSn solder (fig.32 #231). It would have been obvious to one of ordinary skill in the art at the time of the invention to combine the laser light source of Heidel with the submounts and copper heat sink of Andrews '188 to provide heat dissipation (col.6 line 6) and reduce thermal cross talk between adjacent devices (col.7 lines 3-4), and the AlN material and thickness of the submounts of Andrews '535 as the material provides for proper support and heat conduction away from the devices (col.5 lines 4-26), and additionally incorporate the GaN material and mounting techniques of Kuniyasu to generate 400um

wavelengths for use with photosensitive material ([0008]), remove excess heat from the active region ([0220]), and use bonding material that will not deteriorate while using additional heat removal techniques such as water flow ([0166]).

With respect to claim 8, Heidel, Andrews, and Kuniyasu teach the laser light source as outlined in the rejection to claim 7 above, and Kuniyasu additionally teaches the GaN device to have a light emission region (fig.32 #249), and said metallization layer and said AuSn solder are separated by a groove (fig.32 #273) arranged below the light emission layer. It would have been obvious to one of ordinary skill in the art at the time of the invention to incorporate the groove of Kuniyasu into the laser light source in order to provide additional cooling for the device active regions by placing the cooling mechanism closer to the active region ([0232-233]).

With respect to claim 10, Heidel, Andrews, and Kuniyasu teach the laser light source as outlined in the rejection to claim 1 above, recalling Kuniyasu's use of AuSn solder for the chip to mount connection, and Andrews '535 further teaches the submounts to be soldered to the heat dissipation block (col.5 lines 56-58). Andrews does not teach the solder to be of AuSn. It would have been obvious to one of ordinary skill in the art at the time of the invention to combine the laser light source with the AuSn solder used to solder the submount to the heat dissipation block as the benefits of AuSn solder have been laid out by Kuniyasu as outlined in the rejection to claim 7.

Claim 14 is rejected under 35 U.S.C. 103(a) as being unpatentable over Heidel in view of Andrews '188 and further in view of Kuniyasu.

With respect to claim 14, Heidel teaches the laser apparatus as outlined in the rejection to claim 13, including the diodes to be aligned and the block to be a heat dissipation block, but does not teach the diodes to be mounted junction side down on submounts. Andrews '188 teaches a plurality of semiconductor lasers mounted on a plurality of submounts (fig.4 #'s 86). Kuniyasu further teaches the use of GaN based diode lasers ([0008]) to be flip chip mounted (fig.28, heat sink attached at top surface). It would have been obvious to one of ordinary skill in the art at the time of the invention to combine the laser light source of Heidel with the submounts of Andrews '188 to provide heat dissipation (col.6 line 6) and reduce thermal cross talk between adjacent devices (col.7 lines 3-4), as well as the mounting techniques of Kuniyasu to remove excess heat from the active region ([0220]).

Conclusion

Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL**. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any

extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to TOD T. VAN ROY whose telephone number is (571)272-8447. The examiner can normally be reached on M-F.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Minsun Harvey can be reached on (571)272-1835. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

/TVR/

/Minsun Harvey/
Supervisory Patent Examiner, Art Unit 2828